

# Seung-Boo Jung

## List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

338  
papers

6,028  
citations

37  
h-index

59  
g-index

364  
ext. papers

6,898  
ext. citations

2.7  
avg, IF

6.08  
L-index

#	Paper	IF	Citations
338	Effect of temperature on shear properties of Sn-3.0Ag-0.5Cu and Sn-58Bi solder joints. <i>Journal of Alloys and Compounds</i> , <b>2022</b> , 903, 163987	5.7	0
337	Intermetallic compound transformation and mechanical strength of Ni <sub>3</sub> Sn transient liquid phase sinter-bonded joints in an extreme high-temperature environment. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2022</b> , 33, 6616	2.1	0
336	High-temperature stability of Ni-Sn intermetallic joints for power device packaging. <i>Journal of Alloys and Compounds</i> , <b>2022</b> , 890, 161778	5.7	1
335	Comparative study of interfacial reaction and bonding property of laser- and reflow-soldered SnAgCu/Cu joints. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2022</b> , 33, 7983-7994	2.1	0
334	Fabrication of an IPL-sintered Cu circuit and its electrochemical migration behavior. <i>Journal of Alloys and Compounds</i> , <b>2021</b> , 863, 158726	5.7	2
333	Hybrid transient liquid phase sintering bonding of Sn-3.0Ag-0.5Cu solder with added Cu and Ni for Cu Ni bonding. <i>Applied Surface Science</i> , <b>2021</b> , 551, 149396	6.7	4
332	Effect of Ni(P) thickness in Au/Pd/Ni(P) surface finish on the electrical reliability of Sn3.0Ag0.5Cu solder joints during current-stressing. <i>Journal of Alloys and Compounds</i> , <b>2021</b> , 850, 156729	5.7	5
331	Intense pulsed light surface treatment for improving adhesive bonding of aluminum and carbon fiber reinforced plastic (CFRP). <i>Composite Structures</i> , <b>2021</b> , 258, 113364	5.3	4
330	Enhancement of electrochemical and thermal bonding reliability by forming a Cu <sub>3</sub> Sn intermetallic compound using Cu and Sn58Bi. <i>Journal of Alloys and Compounds</i> , <b>2021</b> , 857, 157595	5.7	2
329	Pressureless Cu-Cu bonding using hybrid Cu-epoxy paste and its reliability. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2021</b> , 32, 3054-3065	2.1	1
328	Interfacial Reactions and Mechanical Properties of Sn-58Bi Solder Joints with Ag Nanoparticles Prepared Using Ultra-Fast Laser Bonding. <i>Materials</i> , <b>2021</b> , 14,	3.5	3
327	Design and analysis of Cu circuit for stretchable electronic circuits using finite element analysis. <i>Microelectronic Engineering</i> , <b>2021</b> , 238, 111510	2.5	1
326	Effects of Ag Flake Addition in Sn-3.0Ag-0.5Cu on Microstructure and Mechanical Properties with High-Temperature Storage Test. <i>Journal of Electronic Materials</i> , <b>2021</b> , 50, 5639-5646	1.9	
325	Thermal Conductivity Measurement Method for the Thin Epoxy Adhesive Joint Layer. <i>Journal of Welding and Joining</i> , <b>2021</b> , 39, 402-408	1.1	1
324	A Study of Transient Liquid Phase Bonding Using an Ag-Sn3.0Ag0.5Cu Hybrid Solder Paste. <i>Journal of Welding and Joining</i> , <b>2021</b> , 39, 376-383	1.1	1
323	Mechanical reliability of Cu cored solder ball in flip chip package under thermal shock test. <i>Microelectronics Reliability</i> , <b>2020</b> , 112, 113918	1.2	1
322	Effects of Ni(P) layer thickness and Pd layer type in thin-Au/Pd/Ni(P) surface finishes on interfacial reactions and mechanical strength of Sn58Bi solder joints during aging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 19852-19874	2.1	

321	Fabrication of Novel Ag Flake Composite Films Using a CMC/PEI Cross-Linking Process. <i>Electronic Materials Letters</i> , <b>2020</b> , 16, 332-339	2.9	2
320	Ultrafast Photonic Soldering with Sn58Bi Using Intense Pulsed Light Energy. <i>Advanced Engineering Materials</i> , <b>2020</b> , 22, 2000179	3.5	3
319	Thermal and Thermomechanical Behaviors of the Fan-Out Package With Embedded Ag Patterns. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2020</b> , 10, 1432-1437	1.7	
318	Effect of Ag-decorated MWCNT on the mechanical and thermal property of Sn58Bi solder joints for FCLED package. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 10170-10176	2.1	3
317	Pressureless transient liquid phase bonding using SAC305 with hybrid Ag particles and its reliability under high-temperature storage test. <i>Materialia</i> , <b>2020</b> , 12, 100808	3.2	3
316	Interfacial reactions and mechanical properties of Sn3.0Ag0.5Cu solder with pure Pd or Pd(P) layers containing thin-Au/Pd/Ni(P) surface-finished PCBs during aging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 4027-4039	2.1	0
315	Fast formation of Cu-Sn intermetallic joints using pre-annealed Sn/Cu/Sn composite preform for high-temperature bonding applications. <i>Thin Solid Films</i> , <b>2020</b> , 698, 137873	2.2	5
314	Effect of epoxy mold compound and package dimensions on the thermomechanical properties of a fan-out package. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 6835-6842	2.1	6
313	Bonding of power device to ceramic substrate using Sn-coated Cu micro paste for high-temperature applications. <i>Applied Surface Science</i> , <b>2020</b> , 515, 146060	6.7	13
312	Transient Liquid Phase Sintering of Ni and Sn-58Bi on Microstructures and Mechanical Properties for Ni/Ni Bonding. <i>Electronic Materials Letters</i> , <b>2020</b> , 16, 347-354	2.9	2
311	Fabrication and characterization of Ag flake hybrid circuits with IPL-sintering. <i>Journal of Materials Science and Technology</i> , <b>2020</b> , 53, 13-18	9.1	3
310	Effects of crystalline and amorphous Pd layers on initial interfacial reactions at Sn-3.0Ag-0.5Cu/thin-Au/Pd/Ni(P) solder joints. <i>Applied Surface Science</i> , <b>2020</b> , 503, 144339	6.7	11
309	Effect of SDBS on the oxidation reliability of screen-printed Cu circuits. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 3035-3041	2.1	1
308	Microstructures and thermal properties of Ag-CNT/Cu composites fabricated by friction stir welding. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 2280-2287	2.1	2
307	Effects of a phosphorous-containing Pd layer in a thin-ENEPIG surface finish on the interfacial reactions and mechanical strength of a Sn58Bi solder joint. <i>Journal of Alloys and Compounds</i> , <b>2020</b> , 820, 153396	5.7	6
306	Microstructures and Mechanical Properties of Sn-58 wt.% Bi Solder with Ag-Decorated Multiwalled Carbon Nanotubes Under 85°C/85% Relative Humidity Environmental Conditions. <i>Journal of Electronic Materials</i> , <b>2020</b> , 49, 1527-1533	1.9	3
305	Mechanical properties of Sn-58 wt.%Bi solder containing Ag-decorated MWCNT with thermal aging tests. <i>Journal of Alloys and Compounds</i> , <b>2020</b> , 820, 153077	5.7	15
304	Mechanical, electrical, and thermal reliability of Sn-58wt.%Bi solder joints with Ag-decorated MWCNT for LED package component during aging treatment. <i>Composites Part B: Engineering</i> , <b>2020</b> , 182, 107617	10	9

303	Mechanical properties and microstructural evolution of solder alloys fabricated using laser-assisted bonding. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 22926-22932	2.1	3
302	Bending reliability of Ni/MWCNT composite solder with a differential structure. <i>Microelectronics Reliability</i> , <b>2020</b> , 113, 113934	1.2	2
301	Mechanical Properties of Cu-Core Solder Balls with ENEPIG Surface Finish. <i>Journal of Electronic Materials</i> , <b>2020</b> , 49, 6073-6079	1.9	1
300	Fast formation of Ni/Sn intermetallic joints using Ni/Sn paste for high-temperature bonding applications. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2020</b> , 31, 15048-15060	2.1	8
299	The Fabrication of Ni-MWCNT Composite Solder and Its Reliability Under High Relative Humidity and Temperature. <i>Journal of Electronic Materials</i> , <b>2020</b> , 49, 6746-6753	1.9	0
298	Electromigration Behavior of Cu Core Solder Joints Under High Current Density. <i>Electronic Materials Letters</i> , <b>2020</b> , 16, 513-519	2.9	2
297	Growth kinetics of intermetallic compound layers at the interface during laser-assisted bonding depending on surface finish <b>2020</b> ,		1
296	Pressureless transient liquid phase sintering bonding in air using Ni and Sn58Bi for high-temperature packaging applications. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 18848-18857	2.1	6
295	A UV-responsive pressure sensitive adhesive for damage-free fabrication of an ultrathin imperceptible mechanical sensor with ultrahigh optical transparency. <i>Journal of Materials Chemistry A</i> , <b>2019</b> , 7, 22588-22595	13	16
294	Effect of Sn-Decorated MWCNTs on the Mechanical Reliability of Sn58Bi Solder. <i>Electronic Materials Letters</i> , <b>2019</b> , 15, 693-701	2.9	9
293	Thermal and mechanical property of FCLED package component interconnected with Sn/MWCNT composite solder. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 12869-12875	2.1	2
292	Effects of Ni layer thickness of thin-ENEPIG surface finishes on the interfacial reactions and shear strength of Sn-3.0Ag0.5Cu solder joints during aging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 12911-12923	2.1	2
291	Fabrication of IPL-Sintered Ag-MWCNT composite circuits and their flexibility characteristics. <i>Journal of Alloys and Compounds</i> , <b>2019</b> , 794, 341-346	5.7	7
290	The effect of pH on synthesizing Ni-decorated MWCNTs and its application for Sn-58Bi solder. <i>Current Applied Physics</i> , <b>2019</b> , 19, 1182-1186	2.6	7
289	Effect of black residue on the mechanical properties of Sn-58Bi epoxy solder joints. <i>Microelectronic Engineering</i> , <b>2019</b> , 216, 111055	2.5	2
288	Optimal Ni(P) thickness and reliability evaluation of thin-Au/Pd(P)/Ni(P) surface-finish with Sn-3.0Ag-0.5Cu solder joints. <i>Journal of Alloys and Compounds</i> , <b>2019</b> , 805, 1013-1024	5.7	11
287	Effect of epoxy content in Ag nanoparticle paste on the bonding strength of MLCC packages. <i>Applied Surface Science</i> , <b>2019</b> , 495, 143487	6.7	10
286	Effects of Cu Opening Size on the Mechanical Properties of Epoxy-Contained Sn-58Bi Solder Joints. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2019</b> , 19, 6437-6443	1.3	

285	Nickel in transient liquid phase sintering with high bonding strength for high-temperature power applications. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 20205-20212	2.1	5
284	Thermomechanical Properties of Fan-Out Wafer Level Package Fabricated with Various Epoxy Mold Compound <b>2019</b> ,		1
283	Effect of Sintering Conditions on Microstructure and Mechanical Strength of Cu Micro-Particle Sintered Joints for High-Power Semiconductor Module Applications. <i>Journal of Welding and Joining</i> , <b>2019</b> , 37, 26-34	1.1	6
282	The Effect of Environmental Test on the Shear Strength of the Ultrasonic bonded Cu Terminal for Power Module. <i>Journal of Welding and Joining</i> , <b>2019</b> , 37, 1-6	1.1	1
281	Microstructures and Mechanical Properties of the Sn58wt.%Bi Composite Solders with Sn Decorated MWCNT Particles. <i>Journal of Electronic Materials</i> , <b>2019</b> , 48, 1746-1753	1.9	5
280	Pressureless die attach by transient liquid phase sintering of Cu nanoparticles and Sn-58Bi particles assisted by polyvinylpyrrolidone dispersant. <i>Journal of Alloys and Compounds</i> , <b>2019</b> , 781, 657-663	5.7	12
279	Effect of PVP on fabrication of Cu nanoparticles using an electrical wire explosion method. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 4079-4084	2.1	3
278	Electromigration behaviors of Sn58%Bi solder containing Ag-coated MWCNTs with OSP surface finished PCB. <i>Journal of Alloys and Compounds</i> , <b>2019</b> , 775, 581-588	5.7	17
277	Transparent and flexible high frequency transmission lines based on composite structure comprising silver nanowires and polyvinyl butyral. <i>Composites Science and Technology</i> , <b>2018</b> , 159, 25-32	8.6	9
276	Sequential interfacial reactions of SAC305 solder joints with thin ENEPIG surface finishes. <i>Surface and Interface Analysis</i> , <b>2018</b> , 50, 1046-1050	1.5	6
275	Mechanical Reliability of the Epoxy Sn-58wt.%Bi Solder Joints with Different Surface Finishes Under Thermal Shock. <i>Journal of Electronic Materials</i> , <b>2018</b> , 47, 4165-4169	1.9	7
274	RF characteristics of flexible circuits patterned with hybrid Ag paste. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2018</b> , 29, 5074-5081	2.1	6
273	Comparative study of ENEPIG and thin ENEPIG as surface finishes for SAC305 solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2018</b> , 29, 4724-4731	2.1	9
272	Fabrication of Ag circuit embedded in PDMS substrate and its mechanical and electrical property with variations of photonic energy. <i>Journal of Alloys and Compounds</i> , <b>2018</b> , 748, 898-904	5.7	4
271	Cu-Sn Intermetallic Compound Joints for High-Temperature Power Electronics Applications. <i>Journal of Electronic Materials</i> , <b>2018</b> , 47, 430-435	1.9	32
270	Effect of surface finish metallization on mechanical strength of Ag sintered joint. <i>Microelectronic Engineering</i> , <b>2018</b> , 198, 15-21	2.5	11
269	1.4 $\mu$ m-Thick Transparent Radio Frequency Transmission Lines Based on Instant Fusion of Polyethylene Terephthalate Through Surface of Ag Nanowires. <i>Electronic Materials Letters</i> , <b>2018</b> , 14, 599-609	2.9	5
268	Effect of Epoxy on Mechanical Property of SAC305 Solder Joint with Various Surface Finishes Under 3-Point Bend Test. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2018</b> , 18, 6316-6320	1.3	2

267	Microstructures and Drop Impact Test of SAC305, Sn58%Bi and Epoxy Sn58%Bi Solder Joint on the OSP Surface Finished PCB Substrate. <i>Journal of Welding and Joining</i> , <b>2018</b> , 36, 14-20	1.1	3
266	Effect of Thin ENEPIG Plating Thickness on Interfacial Reaction and Brittle Fracture Rate of Sn-3.0Ag-0.5Cu Solder Joints. <i>Journal of Welding and Joining</i> , <b>2018</b> , 36, 52-60	1.1	1
265	Thermal Resistance Analysis of Light-Emitting Diode Modules with Thermal Via Structure. <i>Journal of Electronic Materials</i> , <b>2018</b> , 47, 7323-7330	1.9	0
264	Effect of Sintering Conditions on the Mechanical Strength of Cu-Sintered Joints for High-Power Applications. <i>Materials</i> , <b>2018</b> , 11,	3.5	17
263	Mechanical Property of SAC305 Ball-Grid Array and Epoxy Sn-58Bi Solder Joints with 85 °C/85% Relative Humidity Environmental Conditions. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2018</b> , 18, 6162-6166	1.3	1
262	Enhancing adhesion strength of photonic sintered screen-printed Ag circuit by atmospheric pressure plasma. <i>Microelectronic Engineering</i> , <b>2018</b> , 202, 37-41	2.5	7
261	Synergistic effect of Indium and Gallium co-doping on growth behavior and physical properties of hydrothermally grown ZnO nanorods. <i>Scientific Reports</i> , <b>2017</b> , 7, 41992	4.9	40
260	Cu <sub>6</sub> Sn and Ni <sub>6</sub> Sn transient liquid phase bonding for die-attach technology applications in high-temperature power electronics packaging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2017</b> , 28, 7827-7833	2.1	37
259	Enhancement of Cu pillar bumps by electroless Ni plating. <i>Microelectronic Engineering</i> , <b>2017</b> , 180, 52-55	2.5	4
258	Interfacial reactions and mechanical strength of Sn-3.0Ag-0.5Cu/Ni/Cu and Au-20Sn/Ni/Cu solder joints for power electronics applications. <i>Microelectronics Reliability</i> , <b>2017</b> , 71, 119-125	1.2	30
257	Fabrication of the hybrid Ag paste combined by Ag nanoparticle and micro Ag flake and its flexibility. <i>Journal of Alloys and Compounds</i> , <b>2017</b> , 699, 1186-1191	5.7	16
256	Die-attach for power devices using the Ag sintering process: Interfacial microstructure and mechanical strength. <i>Metals and Materials International</i> , <b>2017</b> , 23, 958-963	2.4	19
255	Photo-induced fabrication of Ag nanowire circuitry for invisible, ultrathin, conformable pressure sensors. <i>Journal of Materials Chemistry C</i> , <b>2017</b> , 5, 9986-9994	7.1	26
254	The reliability of ultrasonic bonded Cu to Cu electrode for 3D TSV stacking. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2017</b> , 28, 16467-16475	2.1	4
253	Microstructure and mechanical properties of a B4C particle-reinforced Cu matrix composite fabricated by friction stir welding. <i>Journal of Alloys and Compounds</i> , <b>2017</b> , 693, 688-691	5.7	12
252	Interfacial reactions and mechanical strength of Sn-3.0Ag-0.5Cu/0.1um-Ni thin ENEPIG solder joint. <i>Journal of Welding and Joining</i> , <b>2017</b> , 35, 51-58	1.1	5
251	Solderability of thin ENEPIG plating Layer for Fine Pitch Package application. <i>Journal of the Microelectronics and Packaging Society</i> , <b>2017</b> , 24, 83-90		6
250	Effect of Sodium Dodecylbenzene Sulfonate Contents on Oxide Behavior in Cu Nanopaste. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2017</b> , 17, 7497-7501	1.3	

249	Microstructures and mechanical properties of MgOp/SPHC metal matrix composites joint by friction stir welding. <i>Journal of Composite Materials</i> , <b>2016</b> , 50, 1581-1586	2.7	1
248	Facet-controlled anatase TiO <sub>2</sub> nanoparticles through various fluorine sources for superior photocatalytic activity. <i>Nanotechnology</i> , <b>2016</b> , 27, 395604	3.4	8
247	Fabrication of Cu/MWNT nanocomposite and its electrochemical migration behaviors. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2016</b> , 27, 9676-9682	2.1	1
246	Effects of Aging Treatment on Mechanical Properties of Sn-58Bi Epoxy Solder on ENEPIG-Surface-Finished PCB. <i>Journal of Electronic Materials</i> , <b>2016</b> , 45, 5895-5903	1.9	14
245	Morphology Control in Anatase TiO <sub>2</sub> Mesocrystals Through Hydrofluoride Incorporation for Photocatalytic Application. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2016</b> , 16, 10592-10596	1.3	3
244	Effect of Plasma Surface Finish on Wettability and Mechanical Properties of SAC305 Solder Joints. <i>Journal of Electronic Materials</i> , <b>2016</b> , 45, 6184-6191	1.9	7
243	Drop Reliability of Epoxy-contained Sn-58 wt.%Bi Solder Joint with ENIG and ENEPIG Surface Finish Under Temperature and Humidity Test. <i>Journal of Electronic Materials</i> , <b>2016</b> , 45, 3651-3658	1.9	24
242	Electrically and mechanically enhanced Ag nanowires-colorless polyimide composite electrode for flexible capacitive sensor. <i>Applied Surface Science</i> , <b>2016</b> , 380, 223-228	6.7	22
241	Enhanced Photocatalytic Activity of ZnO Nanorods with Tubular Facet Synthesized by Hydrothermal Method. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2016</b> , 16, 11164-11168	1.3	4
240	Application of the Taguchi Method to Optimize Graphene Coatings on Copper Nanoparticles Formed Using a Solid Carbon Source. <i>Materials Transactions</i> , <b>2016</b> , 57, 1177-1182	1.3	1
239	Effects of Hydrothermal Temperature on Crystallinity, Microstructure, and Photocatalytic Activity of Anatase TiO <sub>2</sub> Mesocrystals. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2016</b> , 16, 11153-11157	1.3	1
238	Adhesion of PDMS substrates assisted by Plasma Graft Polymerization. <i>Surface and Interface Analysis</i> , <b>2016</b> , 48, 597-600	1.5	1
237	Board Level Drop Reliability of Epoxy-Containing Sn-58 mass% Bi Solder Joints with Various Surface Finishes. <i>Materials Transactions</i> , <b>2016</b> , 57, 466-471	1.3	9
236	Effect of Hygrothermal Treatment on Reliability of Thermo-Compression Bonded FPCB/RPCB Contact Joints. <i>Materials Transactions</i> , <b>2016</b> , 57, 716-720	1.3	
235	Effects of Precursor Concentration on Morphology of MoS <sub>2</sub> Nanosheets by Hydrothermal Synthesis. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2016</b> , 16, 11548-11551	1.3	11
234	Electromigration effect on Sn-58 % Bi solder joints with various substrate metallizations under current stress. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2016</b> , 27, 1105-1112	2.1	11
233	Effects of oxidation on reliability of screen-printed silver circuits for radio frequency applications. <i>Microelectronics Reliability</i> , <b>2016</b> , 63, 120-124	1.2	2
232	Interfacial reaction and mechanical properties between low melting temperature Sn58Bi solder and various surface finishes during reflow reactions. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 1649-1660	2.1	11

231	Hydrothermally Grown In-doped ZnO Nanorods on p-GaN Films for Color-tunable Heterojunction Light-emitting-diodes. <i>Scientific Reports</i> , <b>2015</b> , 5, 10410	4.9	51
230	Fabrication of Ag-MWNT nanocomposite paste for high-power LED package. <i>Current Applied Physics</i> , <b>2015</b> , 15, S36-S41	2.6	16
229	Evaluation of the Bondability of the Epoxy-Enhanced Sn-58Bi Solder with ENIG and ENEPIG Surface Finishes. <i>Journal of Electronic Materials</i> , <b>2015</b> , 44, 4637-4645	1.9	14
228	The critical role of Ag nanowires in the improvement of conductivity and flexibility of circuits fabricated with hybrid Ag nanopaste. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 8644-8651	2.1	7
227	Effects of Ag content on the reliability of LED package component with SnBiAg solder. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 8707-8713	2.1	19
226	Enhancing Adhesion of Screen-Printed Silver Nanopaste Films. <i>Advanced Materials Interfaces</i> , <b>2015</b> , 2, 1500283	4.6	19
225	Effect of Radio Frequency Plasma Treatment on Evaporation Behavior and Characteristics of RuCr Alloy Powder. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2015</b> , 15, 8424-8	1.3	3
224	Microwave Sintering of Silver Nanoink for Radio Frequency Applications. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2015</b> , 15, 2333-7	1.3	8
223	Interfacial reaction and intermetallic compound formation of SnAg/ENIG and SnAg/ENEPIG solder joints. <i>Journal of Alloys and Compounds</i> , <b>2015</b> , 627, 276-280	5.7	29
222	Effects of Polyvinylpyrrolidone Molecular Weight on Adhesion Strength of Screen-Printed Cu Circuits to Polyimide Substrate. <i>Nanoscience and Nanotechnology Letters</i> , <b>2015</b> , 7, 999-1003	0.8	3
221	Fabrication of SiCp/2024 Composite Alloys Using Friction Stir Welding and Its Mechanical Properties. <i>Science of Advanced Materials</i> , <b>2015</b> , 7, 1535-1539	2.3	2
220	Effect of rare earth metal Ce addition to Sn-Ag solder on interfacial reactions with Cu substrate. <i>Metals and Materials International</i> , <b>2014</b> , 20, 515-519	2.4	5
219	Electrical properties and electrochemical migration characteristics of directly printed Ag patterns with various sintering conditions. <i>Microelectronics Reliability</i> , <b>2014</b> , 54, 410-416	1.2	19
218	Design and fabrication of screen-printed silver circuits for stretchable electronics. <i>Microelectronic Engineering</i> , <b>2014</b> , 120, 216-220	2.5	41
217	Effect of atmospheric-pressure plasma treatment on the adhesion characteristics of screen-printed Ag nanoparticles on polyimide. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2014</b> , 14, 9448-53	1.3	2
216	Screen-printed Cu circuit for low-Cost fabrication and its electrochemical migration characteristics. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2014</b> , 14, 9493-7	1.3	5
215	Effect of Ag nanowire addition into nanoparticle paste on the conductivity of Ag patterns printed by gravure offset method. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2014</b> , 14, 8808-12	1.3	5
214	Electrical and electrochemical migration characteristics of Ag/Cu nanopaste patterns. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2014</b> , 14, 8915-9	1.3	2



213	Effect of surface finishes on electromigration reliability in eutectic Sn58Bi solder joints. <i>Microelectronic Engineering</i> , <b>2014</b> , 120, 77-84	2.5	25
212	Mechanical property of the epoxy-contained Sn58Bi solder with OSP surface finish. <i>Journal of Alloys and Compounds</i> , <b>2014</b> , 615, S411-S417	5.7	36
211	Effect of Aging treatment and Epoxy on Bonding Strength of Sn-58Bi solder and OSP-finished PCB. <i>Journal of the Microelectronics and Packaging Society</i> , <b>2014</b> , 21, 97-103		6
210	Overview on Thermal Management Technology for High Power Device Packaging. <i>Journal of the Microelectronics and Packaging Society</i> , <b>2014</b> , 21, 13-21		1
209	Enhanced electrical and mechanical properties of silver nanoplatelet-based conductive features direct printed on a flexible substrate. <i>ACS Applied Materials &amp; Interfaces</i> , <b>2013</b> , 5, 5908-13	9.5	34
208	Electrochemical migration of Ag nanoparticle patterns controlled by atmospheric-pressure plasma. <i>Microelectronic Engineering</i> , <b>2013</b> , 106, 27-32	2.5	8
207	Joint reliability evaluation of thermo-compression bonded FPCB/RPCB joints under high temperature storage test. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 2036-2042	1.2	7
206	The characteristics of Cu nanopaste sintered by atmospheric-pressure plasma. <i>Microelectronic Engineering</i> , <b>2013</b> , 107, 121-124	2.5	21
205	Effect of surface treatment on the high-speed drop reliability of Pb-free solder interconnect. <i>Thin Solid Films</i> , <b>2013</b> , 547, 120-124	2.2	3
204	Reliability of chip on glass module fabricated with direct printing method. <i>Microelectronic Engineering</i> , <b>2013</b> , 107, 114-120	2.5	2
203	Behavior of $\beta$ phase (Al3Mg2) in AA 5083 during friction stir welding. <i>Intermetallics</i> , <b>2013</b> , 35, 120-127	3.5	45
202	The microstructures and mechanical properties of friction stir welded AZ31 with CaO Mg alloys. <i>Journal of Alloys and Compounds</i> , <b>2013</b> , 554, 162-168	5.7	13
201	Microstructure and mechanical property of A356 based composite by friction stir processing. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2013</b> , 23, 335-340	3.3	29
200	Effects of atmospheric pressure plasma surface treatments on the patternability and electrical property of screen-printed Ag nanopaste. <i>Metals and Materials International</i> , <b>2013</b> , 19, 829-834	2.4	1
199	Electrochemical migration of directly printed Ag electrodes using Ag paste with epoxy binder. <i>Microelectronic Engineering</i> , <b>2013</b> , 103, 1-6	2.5	20
198	Electrochemical migration behavior of silver nanopaste screen-printed for flexible and printable electronics. <i>Current Applied Physics</i> , <b>2013</b> , 13, S190-S194	2.6	22
197	Characterization of Ag-Pd nanocomposite paste for electrochemical migration resistance. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2013</b> , 13, 7620-4	1.3	4
196	Synthesis of Ag nanowires for the fabrication of transparent conductive electrode. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2013</b> , 13, 6244-8	1.3	9

195	Characterization of reliability of printed indium tin oxide thin films. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2013</b> , 13, 7770-3	1.3	1
194	Thermal and Mechanical Properties of Flip Chip Package with Au Stud Bump. <i>Materials Transactions</i> , <b>2013</b> , 54, 905-910	1.3	3
193	Peel strengths of the Composite Structure of Metal and Metal Oxide Laminate. <i>Journal of the Microelectronics and Packaging Society</i> , <b>2013</b> , 20, 13-16		
192	Evaluation of drop reliability of Sn <sub>67</sub> Pb solder/Cu joints using a high speed lap-shear test. <i>Microelectronic Engineering</i> , <b>2012</b> , 91, 147-153	2.5	14
191	Thermo-compression bonding of electrodes between FPCB and RPCB by using Pb-free solders. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2012</b> , 23, 41-47	2.1	5
190	Effects of Plasma Polymerized Acrylic Acid Film on the Adhesion of Ag Tracks Screen-Printed on Polyimide <b>2012</b> , 88, 337-349		9
189	The influence of MWNT composite on the stretchability of conductive nanopaste screen-printed on elastomeric substrate. <i>Current Applied Physics</i> , <b>2012</b> , 12, S99-S103	2.6	10
188	Fabrication of SiCp/AA5083 composite via friction stir welding. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2012</b> , 22, s634-s638	3.3	32
187	Effect of SiC particles on microstructure and mechanical property of friction stir processed AA6061-T4. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2012</b> , 22, s614-s618	3.3	30
186	Microstructure and adhesion characteristics of a silver nanopaste screen-printed on Si substrate. <i>Nanoscale Research Letters</i> , <b>2012</b> , 7, 49	5	12
185	Electrochemical migration characteristics of screen-printed silver patterns on FR-4 substrate. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2012</b> , 12, 3219-23	1.3	6
184	Effect of gold immersion time on the electrochemical migration property of electroless nickel/immersion gold surface finishing. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2012</b> , 12, 3506-10	1.3	4
183	Effects of sintering conditions on microstructure and characteristics of screen-printed Ag thin film. <i>Electronic Materials Letters</i> , <b>2012</b> , 8, 309-314	2.9	14
182	Mechanical strength and fracture mode transition of Sn-58Bi epoxy solder joints under high-speed shear test. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2012</b> , 23, 1515-1520	2.1	7
181	Adhesion characteristics of silver tracks screen-printed on polyimide with an environmental reliability test. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2012</b> , 12, 5769-73	1.3	4
180	Ductile fracture mechanism of low-temperature In-48Sn alloy joint under high strain rate loading. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2012</b> , 12, 3259-63	1.3	2
179	Microstructures and Mechanical Properties of Friction Stir Welded 2.25Cr&ndash;1Mo Steel. <i>Materials Transactions</i> , <b>2012</b> , 53, 1022-1025	1.3	6
178	Sequential interfacial intermetallic compound formation of Cu <sub>6</sub> Sn <sub>5</sub> and Ni <sub>3</sub> Sn <sub>4</sub> between SnAgCu solder and ENEPIG substrate during a reflow process. <i>Journal of Alloys and Compounds</i> , <b>2011</b> , 509, L153-L156	5.7	55

177	Formation of intermetallic compounds in Al and Mg alloy interface during friction stir spot welding. <i>Intermetallics</i> , <b>2011</b> , 19, 125-130	3.5	92
176	Hybrid Friction Stir Welding of High-carbon Steel. <i>Journal of Materials Science and Technology</i> , <b>2011</b> , 27, 127-130	9.1	29
175	Electrical characteristics of printed Ag nanopaste on polyimide substrate. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2011</b> , 11, 1468-71	1.3	4
174	Effect of sintering temperature on electrical characteristics of screen-printed Ag nanopaste on FR4 substrate. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2011</b> , 11, 5915-20	1.3	5
173	Evaluation of the flexibility of silver circuits screen-printed on polyimide with an environmental reliability test. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2011</b> , 11, 5806-11	1.3	8
172	High frequency characteristics of printed Cu conductive circuit. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2011</b> , 11, 537-40	1.3	8
171	Flexibility of silver conductive circuits screen-printed on a polyimide substrate. <i>Journal of Nanoscience and Nanotechnology</i> , <b>2011</b> , 11, 1493-8	1.3	17
170	Effect of Pd Addition in ENIG Surface Finish on Drop Reliability of Sn-Ag-Cu Solder Joint. <i>Materials Transactions</i> , <b>2011</b> , 52, 1553-1559	1.3	19
169	Effect of peak current density on the mechanical and electrical properties of copper/polyimide fabricated by a pulsed electrodeposition process. <i>Current Applied Physics</i> , <b>2011</b> , 11, S128-S131	2.6	4
168	Interfacial reaction between AuSn solder and Au/Ni-metallized Kovar. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 84-90	2.1	19
167	Effect of adding Ce on interfacial reactions between SnAg solder and Cu. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 745-750	2.1	14
166	Effects of different kinds of seed layers and heat treatment on adhesion characteristics of Cu/(Cr or NiCr)/PI interfaces in flexible printed circuits. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 790-796	2.1	5
165	Microstructure of interfacial reaction layer in SnAgCu/electroless Ni (P) solder joint. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 1308-1312	2.1	3
164	Microstructure, Electrical Properties, and Electrochemical Migration of a Directly Printed Ag Pattern. <i>Journal of Electronic Materials</i> , <b>2011</b> , 40, 35-41	1.9	20
163	Effects of Different Kinds of Underfills and Temperature/Humidity Treatments on Drop Reliability of Board-Level Packages. <i>Journal of Electronic Materials</i> , <b>2011</b> , 40, 224-231	1.9	9
162	Comparative Study of ENIG and ENEPIG as Surface Finishes for a Sn-Ag-Cu Solder Joint. <i>Journal of Electronic Materials</i> , <b>2011</b> , 40, 1950-1955	1.9	67
161	Effect of Non-conductive Film on the Reliability of Multi-chip Package Bonded Using Ultrasonic Energy. <i>Journal of Adhesion Science and Technology</i> , <b>2011</b> , 25, 2475-2482	2	1
160	Development and evaluation of a Cu composite sheet with embedded high electric conduction path for new interconnect material. <i>Current Applied Physics</i> , <b>2011</b> , 11, S283-S288	2.6	1

159	Effect of thermal treatment on adhesion strength of Cu/NiCr/polyimide flexible copper clad laminate fabricated by roll-to-roll process. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 718-723	2.5	15
158	Effect of heat treatment on physical and electrical characteristics of conductive circuits printed on Si substrate. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 791-796	2.5	0
157	Influence of current density on mechanical reliability of Sn <sub>3</sub> .5Ag BGA solder joint. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 709-714	2.5	5
156	Ultrasonic bonding for multi-chip packaging bonded with non-conductive film. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 715-717	2.5	1
155	Fabrication and adhesion strength of Cu/NiCr/polyimide films for flexible printed circuits. <i>Microelectronic Engineering</i> , <b>2011</b> , 88, 1024-1027	2.5	16
154	Mechanical Reliability of Sn-Ag BGA Solder Joints With Various Electroless Ni-P and Ni-B Plating Layers. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2010</b> , 33, 222-228		7
153	Reliability of Fine-Pitch Flip-Chip (COG) Bonding with Non-Conductive Film Using Ultrasonic Energy <b>2010</b> , 86, 470-479		4
152	Effects of cerium content on wettability, microstructure and mechanical properties of SnAgTe solder alloys. <i>Journal of Alloys and Compounds</i> , <b>2010</b> , 499, 154-159	5.7	37
151	Effects of third element and surface finish on interfacial reactions of SnAgCu (or Ni)/(Cu or ENIG) solder joints. <i>Journal of Alloys and Compounds</i> , <b>2010</b> , 506, 331-337	5.7	26
150	Comparison of Interfacial Stability of Pb-Free Solders (Sn <sub>3</sub> .5Ag, Sn <sub>3</sub> .5Ag <sub>0</sub> .7Cu, and Sn <sub>0</sub> .7Cu) on ENIG-Plated Cu During Aging. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2010</b> , 33, 64-70		20
149	Effect of Cr Thickness on Adhesion Strength of Cu/Cr/Polyimide Flexible Copper Clad Laminate Fabricated by Roll-to-Roll Process. <i>Materials Transactions</i> , <b>2010</b> , 51, 85-89	1.3	9
148	Electromigration Behavior of through-Si-via (TSV) Interconnect for 3-D Flip Chip Packaging. <i>Materials Transactions</i> , <b>2010</b> , 51, 1020-1027	1.3	1
147	Effect of Pin Shapes on Joint Characteristics of Friction Stir Spot Welded AA5J32 Sheet. <i>Materials Transactions</i> , <b>2010</b> , 51, 1028-1032	1.3	38
146	Microstructure and Mechanical Properties of Friction Stir Spot Welded Galvanized Steel. <i>Materials Transactions</i> , <b>2010</b> , 51, 1044-1050	1.3	30
145	Structure&Properties Relations in Friction Stir Spot Welded Low Carbon Steel Sheets for Light Weight Automobile Body. <i>Materials Transactions</i> , <b>2010</b> , 51, 399-403	1.3	17
144	Failure mechanism of Pb-bearing and Pb-free solder joints under high-speed shear loading. <i>Metals and Materials International</i> , <b>2010</b> , 16, 7-12	2.4	22
143	Effect of Ni-Cr seed layer thickness on the adhesion characteristics of flexible copper clad laminates fabricated using a roll-to-roll process. <i>Metals and Materials International</i> , <b>2010</b> , 16, 779-784	2.4	13
142	Characterization of direct patterned Ag circuits for RF application. <i>Microelectronic Engineering</i> , <b>2010</b> , 87, 379-382	2.5	22

141	Effect of laminating parameters on the adhesion property of flexible copper clad laminate with adhesive layer. <i>International Journal of Adhesion and Adhesives</i> , <b>2010</b> , 30, 30-35	3.4	22
140	Effect of multiple reflows on interfacial reaction and shear strength of SnAg electroplated solder bumps for flip chip package. <i>Microelectronic Engineering</i> , <b>2010</b> , 87, 517-521	2.5	21
139	Fabrication and Characterization of the $\text{MgB}_2$ Bulk Superconductors Doped by Carbon Nanotubes. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2009</b> , 19, 2767-2770	1.8	1
138	FAILURE BEHAVIORS OF FLIP CHIP SOLDER JOINTS UNDER VARIOUS LOADING CONDITIONS OF HIGH-SPEED SHEAR TEST. <i>International Journal of Modern Physics B</i> , <b>2009</b> , 23, 1809-1815	1.1	2
137	Effect of Additives on Microstructure and Mechanical Properties of Nickel Plate/Mask Fabricated by Electroforming Process. <i>Journal of the Electrochemical Society</i> , <b>2009</b> , 156, D108	3.9	11
136	Failure behaviors of BGA solder joints under various loading conditions of high-speed shear test. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2009</b> , 20, 17-24	2.1	15
135	Adhesion characteristics of Cu/NiCr/polyimide flexible copper clad laminates according to Ni:Cr ratio and Cu electroplating layer thickness. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2009</b> , 20, 885-890	2.1	19
134	Effect of Ni-Cr Layer on Adhesion Strength of Flexible Copper Clad Laminate. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 46-53	1.9	12
133	Electromigration Behavior in Sn-37Pb and Sn-3.0Ag-0.5Cu Flip-Chip Solder Joints under High Current Density. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 70-77	1.9	14
132	Evaluation of Electrochemical Migration on Flexible Printed Circuit Boards with Different Surface Finishes. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 902-907	1.9	34
131	Mechanical Property Evaluation of Sn-3.0A-0.5Cu BGA Solder Joints Using High-Speed Ball Shear Test. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 2489-2495	1.9	14
130	Solder joint reliability in flip chip package with surface treatment of ENIG under thermal shock test. <i>Metals and Materials International</i> , <b>2009</b> , 15, 655-660	2.4	11
129	Reliability of Au bump flip chip packages with adhesive materials using four-point bending test. <i>International Journal of Adhesion and Adhesives</i> , <b>2009</b> , 29, 650-655	3.4	12
128	Transmission property of flip chip package with adhesive interconnection for RF applications. <i>Microelectronic Engineering</i> , <b>2009</b> , 86, 314-320	2.5	3
127	Liquid-state and solid-state interfacial reactions of fluxless-bonded Au <sub>20</sub> Sn/ENIG solder joint. <i>Journal of Alloys and Compounds</i> , <b>2009</b> , 469, 108-115	5.7	32
126	Wettability and interfacial reactions of SnAgCu/Cu and SnAgNi/Cu solder joints. <i>Journal of Alloys and Compounds</i> , <b>2009</b> , 486, 142-147	5.7	101
125	Ultrasonic Bonding of Electrodes of Rigid and Flexible Printed Circuit Boards with Non-Conductive Film (NCF) <b>2009</b> , 85, 341-350		2
124	Effects of Underfill Materials and Thermal Cycling on Mechanical Reliability of Chip Scale Package. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 633-638		8

123	Characterization of flexible copper laminates fabricated by Cu electro-plating process. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2009</b> , 19, 965-969	3-3	10
122	Fabrication of two-layer flexible copper clad laminate by electroless-Cu plating on surface modified polyimide. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2009</b> , 19, 970-974	3-3	12
121	Effect of surface finish on interfacial reactions of Cu/SnAgCu/Cu(ENIG) sandwich solder joints. <i>Journal of Alloys and Compounds</i> , <b>2008</b> , 448, 177-184	5-7	30
120	Effect of immersion Ag surface finish on interfacial reaction and mechanical reliability of Sn <sub>3</sub> .5Ag <sub>0.7</sub> Cu solder joint. <i>Journal of Alloys and Compounds</i> , <b>2008</b> , 458, 200-207	5-7	37
119	Effect of reflow numbers on the interfacial reaction and shear strength of flip chip solder joints. <i>Journal of Alloys and Compounds</i> , <b>2008</b> , 458, 253-260	5-7	23
118	Effect of boron content in electroless NiB layer on plating layer properties and soldering characteristics with SnAg solder. <i>Journal of Alloys and Compounds</i> , <b>2008</b> , 466, 73-79	5-7	22
117	Longitudinal Ultrasonic Bonding of Electrodes between Rigid and Flexible Printed Circuit Boards. <i>Japanese Journal of Applied Physics</i> , <b>2008</b> , 47, 4300-4304	1-4	9
116	Analysis of Failure Mechanism in Anisotropic Conductive and Non-Conductive Film Interconnections. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 65-73		17
115	Initial interfacial reaction layers formed in Sn <sub>3</sub> .5Ag solder/electroless NiB plated Cu substrate system. <i>Journal of Materials Research</i> , <b>2008</b> , 23, 2195-2201	2-5	13
114	Microwave Performance of Flip Chip Interconnects With Anisotropic and Non-conductive Films. <i>Journal of Adhesion Science and Technology</i> , <b>2008</b> , 22, 1339-1354	2	2
113	Evaluation of Thermal and Hygro-Thermal Behaviors of Flip Chip Packages With a Non-conductive Paste. <i>Journal of Adhesion Science and Technology</i> , <b>2008</b> , 22, 1355-1364	2	
112	Interfacial reactions and mechanical properties of In <sub>4</sub> 8Sn solder joint with electroplated Au/Ni ball grid array (BGA) substrate after multiple reflows. <i>Journal of Materials Research</i> , <b>2008</b> , 23, 1631-1641	2-5	6
111	Effect of Atmospheric Pressure Plasma Treatment on Transverse Ultrasonic Bonding of Gold Flip-Chip Bump on Glass Substrate. <i>Japanese Journal of Applied Physics</i> , <b>2008</b> , 47, 4309-4313	1-4	6
110	Application of Underfill for Flip-Chip Package Using Ultrasonic Bonding. <i>Japanese Journal of Applied Physics</i> , <b>2008</b> , 47, 4257-4261	1-4	14
109	Microstructures and Mechanical Properties of Double-Friction Stir Welded 2219 Al Alloy. <i>Materials Transactions</i> , <b>2008</b> , 49, 885-888	1-3	6
108	Lap joint properties of FSWed dissimilar formed 5052 Al and 6061 Al alloys with different thickness. <i>Journal of Materials Science</i> , <b>2008</b> , 43, 3296-3304	4-3	68
107	Electrical properties and interfacial reaction of BGA package with underfill. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2008</b> , 19, 75-80	2-1	1
106	Effect of underfill on bending fatigue behavior of chip scale package. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2008</b> , 19, 406-410	2-1	2

105	Characteristics of environmental factor for electrochemical migration on printed circuit board. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2008</b> , 19, 952-956	2.1	29
104	Reliability of Conductive Adhesives as a Pb-free Alternative in Flip-Chip Applications. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 9-16	1.9	17
103	Characterization of Interfacial Reaction Layers Formed Between Sn-3.5Ag Solder and Electroless Ni-Immersion Au-Plated Cu Substrates. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 84-89	1.9	19
102	Mechanical and Electrical Properties of Cu/Sn-3.5Ag/Cu Ball Grid Array (BGA) Solder Joints after Multiple Reflows. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 118-124	1.9	14
101	Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. <i>Microelectronic Engineering</i> , <b>2008</b> , 85, 1967-1970	2.5	23
100	Effect of high-speed loading conditions on the fracture mode of the BGA solder joint. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 1882-1889	1.2	20
99	Thermal degradation of anisotropic conductive film joints under temperature fluctuation. <i>International Journal of Adhesion and Adhesives</i> , <b>2008</b> , 28, 314-320	3.4	10
98	Effect of surface finish material on printed circuit board for electrochemical migration. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 652-656	1.2	47
97	Effects of isothermal aging and temperature/humidity treatment of substrate on joint reliability of Sn <sub>3</sub> .0Ag <sub>0</sub> .5Cu/OSP-finished Cu CSP solder joint. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 1864-1874	1.2	30
96	Mechanical reliability of Sn-rich Au <sub>3</sub> Sn/Ni flip chip solder joints fabricated by sequential electroplating method. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 1857-1863	1.2	25
95	Reliability evaluation of Au <sub>2</sub> 0Sn flip chip solder bump fabricated by sequential electroplating method with Sn and Au. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2008</b> , 473, 119-125	5.3	34
94	Effect of bonding conditions on conduction behavior of anisotropic conductive film interconnection. <i>Metals and Materials International</i> , <b>2008</b> , 14, 373-379	2.4	6
93	Direct Metallization of Gold Nanoparticles on a Polystyrene Bead Surface using Cationic Gold Ligands. <i>Macromolecular Rapid Communications</i> , <b>2007</b> , 28, 634-640	4.8	53
92	Effect of plasma treatment on adhesion characteristics at interfaces between underfill and substrate. <i>International Journal of Adhesion and Adhesives</i> , <b>2007</b> , 27, 200-206	3.4	10
91	Reliability of nickel flip chip bumps with a tin/silver encapsulation on a copper/tin/silver substrate during the bonding process. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2686-2690	2.5	3
90	Characteristic evaluation of electroless nickel/phosphorus deposits with different phosphorus contents. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2552-2557	2.5	56
89	Investigation of interfacial reaction between Au <sub>3</sub> Sn solder and Kovar for hermetic sealing application. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2634-2639	2.5	27
88	Effects of nodule treatment of rolled copper on the mechanical properties of the flexible copper-clad laminate. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2653-2657	2.5	10

87	Reliability of adhesive interconnections for application in display module. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2691-2696	2.5	21
86	Effects of heat treatment and film thickness on microstructure and critical properties of YBCO film processed by TFA-MOD. <i>Physica C: Superconductivity and Its Applications</i> , <b>2007</b> , 451, 118-126	1.3	9
85	Interfacial reaction and joint reliability of fine-pitch flip-chip solder bump using stencil printing method. <i>Microelectronic Engineering</i> , <b>2007</b> , 84, 2640-2645	2.5	5
84	Effect of displacement rate on ball shear properties for Sn <sub>87</sub> Pb and Sn <sub>85.5</sub> Ag BGA solder joints during isothermal aging. <i>Microelectronics Reliability</i> , <b>2007</b> , 47, 2169-2178	1.2	31
83	Dynamic thermodynamic diagram analysis of thermal isomerization of polyisoimide using complex electric modulus properties. <i>Polymer</i> , <b>2007</b> , 48, 3248-3255	3.9	6
82	TEM study on the interfacial reaction between electroless plated Ni <sub>8</sub> /Au UBM and Sn <sub>85.5</sub> Ag solder. <i>Metals and Materials International</i> , <b>2007</b> , 13, 235-238	2.4	2
81	Investigation of interfacial reaction and joint reliability between eutectic Sn <sub>85.5</sub> Ag solder and ENIG-plated Cu substrate during high temperature storage test. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2007</b> , 18, 559-567	2.1	14
80	Au <sub>8</sub> Sn flip-chip solder bump for microelectronic and optoelectronic applications. <i>Microsystem Technologies</i> , <b>2007</b> , 13, 1463-1469	1.7	20
79	Effect of surface finish of substrate on mechanical reliability of In-48Sn solder joints in MOEMS package. <i>Microsystem Technologies</i> , <b>2007</b> , 13, 1567-1573	1.7	13
78	Design of Solder Joint Structure for Flip Chip Package with an Optimized Shear Test Method. <i>Journal of Electronic Materials</i> , <b>2007</b> , 36, 690-696	1.9	4
77	Behavior of Anisotropic Conductive Film Joints Bonded with Various Forces under Temperature Fluctuation. <i>Journal of Electronic Materials</i> , <b>2007</b> , 36, 1199-1205	1.9	4
76	Fabrication of Ni Metal Mask by Electroforming Process Using Wetting Agents. <i>Journal of Electronic Materials</i> , <b>2007</b> , 36, 1510-1515	1.9	5
75	MORPHOLOGY, THERMAL STABILITY, AND SOLDERABILITY OF ELECTROLESS NICKELPHOSPHORUS PLATING LAYER. <i>Surface Review and Letters</i> , <b>2007</b> , 14, 827-832	1.1	12
74	SURFACE MODIFICATION OF PLASMA TREATMENT ON SiO <sub>2</sub> LAYER WITH UNDERFILL. <i>Surface Review and Letters</i> , <b>2007</b> , 14, 849-852	1.1	2
73	Fabrication of the YBCO Films Made by TFA-MOD Using the 211-Process. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2007</b> , 17, 3302-3305	1.8	
72	Reliability analysis of Au <sub>8</sub> Sn flip-chip solder bump fabricated by co-electroplating. <i>Journal of Materials Research</i> , <b>2007</b> , 22, 1219-1229	2.5	24
71	Microstructural evolution and interfacial reactions of fluxless-bonded Au-20Sn/Cu solder joint during reflow and aging. <i>Journal of Materials Research</i> , <b>2007</b> , 22, 2817-2824	2.5	13
70	The Effects of the Humidity and Thickness on YBCO Film Prepared Using the TFA-MOD Method. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2007</b> , 17, 3298-3301	1.8	3



69	Solid-state interfacial reactions between Sn <sub>3</sub> .5Ag <sub>0.7</sub> Cu solder and electroless Ni-immersion Au substrate during high temperature storage test. <i>Journal of Alloys and Compounds</i> , <b>2007</b> , 439, 91-96	5.7	30
68	Thermal and hygroscopic reliability of flip-chip packages with an anisotropic conductive film. <i>Journal of Adhesion Science and Technology</i> , <b>2007</b> , 21, 1071-1087	2	1
67	Characterizations of the Mechanical Properties and Wear Behavior of Ni Plate Fabricated by the Electroforming Process. <i>Korean Journal of Materials Research</i> , <b>2007</b> , 17, 538-543	0.2	
66	Evaluation of solder joint reliability in flip chip package under thermal shock test. <i>Thin Solid Films</i> , <b>2006</b> , 504, 426-430	2.2	15
65	Microstructures and wear property of friction stir welded AZ91 Mg/SiC particle reinforced composite. <i>Composites Science and Technology</i> , <b>2006</b> , 66, 1513-1520	8.6	74
64	Effects of Cr <sub>3</sub> C <sub>2</sub> on the microstructure and mechanical properties of the brazed joints between WC <sub>16</sub> Co and carbon steel. <i>International Journal of Refractory Metals and Hard Materials</i> , <b>2006</b> , 24, 215-221	4.1	55
63	Development of YBCO film approached by TFA-MOD method using the Y <sub>2</sub> Ba <sub>1</sub> Cu <sub>1</sub> O <sub>x</sub> and Ba <sub>3</sub> Cu <sub>5</sub> O <sub>8</sub> powders. <i>Materials Research Society Symposia Proceedings</i> , <b>2006</b> , 946, 1		
62	Effects of reflow and cooling conditions on interfacial reaction and IMC morphology of Sn <sub>3</sub> Cu/Ni solder joint. <i>Journal of Alloys and Compounds</i> , <b>2006</b> , 415, 56-61	5.7	23
61	Reliability studies of Sn <sub>3</sub> Zn/Cu solder joints with aging treatment. <i>Journal of Alloys and Compounds</i> , <b>2006</b> , 407, 141-149	5.7	30
60	Interfacial reactions and shear strength on Cu and electrolytic Au/Ni metallization with Sn-Zn solder. <i>Journal of Materials Research</i> , <b>2006</b> , 21, 1590-1599	2.5	53
59	Interfacial reactions and joint strength of Sn <sub>3</sub> Pb and Sn <sub>3</sub> .5Ag solders with immersion Ag-plated Cu substrate during aging at 150 °C. <i>Journal of Materials Research</i> , <b>2006</b> , 21, 3196-3204	2.5	26
58	Interfacial reactions between In <sub>48</sub> Sn solder and electroless nickel/immersion gold substrate during reflow process. <i>Surface and Interface Analysis</i> , <b>2006</b> , 38, 426-428	1.5	9
57	Characteristic analysis of electroless Ni plating layer for electronic packaging. <i>Surface and Interface Analysis</i> , <b>2006</b> , 38, 440-443	1.5	4
56	Reexamination of the solder ball shear test for evaluation of the mechanical joint strength. <i>International Journal of Solids and Structures</i> , <b>2006</b> , 43, 1928-1945	3.1	20
55	Interfacial reaction of ENIG/Sn-Ag-Cu/ENIG sandwich solder joint during isothermal aging. <i>Microelectronic Engineering</i> , <b>2006</b> , 83, 2329-2334	2.5	30
54	Effects of bonding pressure on the thermo-mechanical reliability of ACF interconnection. <i>Microelectronic Engineering</i> , <b>2006</b> , 83, 2335-2340	2.5	21
53	Evaluation of displacement rate effect in shear test of Sn <sub>3</sub> Ag <sub>0.5</sub> Cu solder bump for flip chip application. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 535-542	1.2	30
52	Development of textured Ni substrates prepared by powder metallurgy and casting. <i>Physica C: Superconductivity and Its Applications</i> , <b>2006</b> , 436, 103-109	1.3	1

51	Effects of electromigration on microstructural evolution of eutectic SnPb flip chip solder bumps. <i>Microelectronic Engineering</i> , <b>2006</b> , 83, 2391-2395	2.5	11
50	High temperature reliability and interfacial reaction of eutectic Sn $\bar{0}$ .7Cu/Ni solder joints during isothermal aging. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 905-914	1.2	19
49	Effect of isothermal aging on the interfacial reactions between Sn $\bar{0}$ .4Cu solder and Cu substrate with or without ENIG plating layer. <i>Surface and Coatings Technology</i> , <b>2006</b> , 200, 4440-4447	4.4	18
48	Investigations of the test parameters and bump structures in the shear test of flip chip solder bump. <i>Thin Solid Films</i> , <b>2006</b> , 504, 405-409	2.2	14
47	Interfacial reactions and growth kinetics for intermetallic compound layer between In $\bar{3}$ 8Sn solder and bare Cu substrate. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 386, 151-156	5.7	85
46	Effects of intermetallic compound on the electrical and mechanical properties of friction welded Cu/Al bimetallic joints during annealing. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 390, 212-219	5.7	241
45	Interfacial reaction and mechanical properties of eutectic Sn $\bar{0}$ .7Cu/Ni BGA solder joints during isothermal long-term aging. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 391, 82-89	5.7	91
44	IMC morphology, interfacial reaction and joint reliability of Pb-free Sn $\bar{3}$ Ag $\bar{0}$ Cu solder on electrolytic Ni BGA substrate. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 392, 247-252	5.7	96
43	Solid state interfacial reaction and joint strength of Sn $\bar{3}$ 7Pb solder with Ni $\bar{3}$ P under bump metallization in flip chip application. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 395, 80-87	5.7	28
42	Interfacial reactions between Sn $\bar{0}$ .4Cu solder and Cu substrate with or without ENIG plating layer during reflow reaction. <i>Journal of Alloys and Compounds</i> , <b>2005</b> , 396, 122-127	5.7	66
41	Microstructural investigation of friction stir welded pure titanium. <i>Materials Letters</i> , <b>2005</b> , 59, 3315-3318	3.3	154
40	Intermetallic Compound Formation and Growth Kinetics in Flip Chip Joints Using Sn $\bar{3}$ Ag $\bar{0}$ .5Cu Solder and Ni $\bar{3}$ P under Bump Metallurgy. <i>Materials Transactions</i> , <b>2005</b> , 46, 1295-1300	1.3	8
39	Induction Brazing of $\bar{\gamma}$ -TiAl to Alloy Steel AISI 4140 Using Filler Metal of Eutectic Ag-Cu Alloy Coated with Ti Film. <i>Materials Transactions</i> , <b>2005</b> , 46, 303-308	1.3	5
38	Microstructure and Mechanical Properties of Sn $\bar{3}$ .7Cu Flip Chip Solder Bumps Using Stencil Printing Method. <i>Materials Transactions</i> , <b>2005</b> , 46, 2366-2371	1.3	6
37	Optimization of shear test for flip chip solder bump using 3-dimensional computer simulation. <i>Microelectronic Engineering</i> , <b>2005</b> , 82, 554-560	2.5	8
36	Interfacial reactions and joint reliability of Sn $\bar{3}$ Zn solder on Cu or electrolytic Au/Ni/Cu BGA substrate. <i>Microelectronic Engineering</i> , <b>2005</b> , 82, 561-568	2.5	26
35	Reliability evaluations of flip chip package under thermal shock test. <i>Microelectronic Engineering</i> , <b>2005</b> , 82, 575-580	2.5	6
34	Effect of aging conditions on interfacial reaction and mechanical joint strength between Sn $\bar{3}$ .0Ag $\bar{0}$ .5Cu solder and Ni $\bar{3}$ P UBM. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , <b>2005</b> , 121, 204-210	3.1	42

33	Effect of substrate metallization on mechanical properties of Sn <sub>3</sub> .5Ag BGA solder joints with multiple reflows. <i>Microelectronic Engineering</i> , <b>2005</b> , 82, 569-574	2.5	32
32	Characterization of the shear test method with low melting point In <sub>48</sub> Sn solder joints. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2005</b> , 397, 145-152	5.3	24
31	Evaluation of solder joint reliability in flip-chip packages during accelerated testing. <i>Journal of Electronic Materials</i> , <b>2005</b> , 34, 1550-1557	1.9	28
30	Reliability of In-48Sn solder/Au/Ni/Cu BGA packages during reflow process. <i>Journal of Electronic Materials</i> , <b>2005</b> , 34, 1565-1572	1.9	19
29	Solid state intermetallic compound layer growth between Sn-8Zn-3Bi solder and bare copper substrate. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2005</b> , 16, 523-528	2.1	9
28	Correlation between the interfacial reaction and mechanical joint strength of the flip chip solder bump during isothermal aging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2005</b> , 16, 603-609	2.1	7
27	Friction welding of TiAl and AISI4140. <i>Journal of Materials Science</i> , <b>2004</b> , 39, 1125-1128	4.3	18
26	Effect of isothermal aging on intermetallic compound layer growth at the interface between Sn-3.5Ag-0.75Cu solder and Cu substrate. <i>Journal of Materials Science</i> , <b>2004</b> , 39, 4211-4217	4.3	45
25	Interfacial reactions and intermetallic compound growth between indium and copper. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2004</b> , 15, 95-98	2.1	11
24	The effect of isothermal aging on the thickness of intermetallic compound layer growth between low melting point solders and Ni-plated Cu substrate. <i>Journal of Electronic Materials</i> , <b>2004</b> , 33, 1561-1566	1.9	6
23	Interfacial reactions and shear strengths between Sn-Ag-based Pb-free solder balls and Au/EN/Cu metallization. <i>Journal of Electronic Materials</i> , <b>2004</b> , 33, 1182-1189	1.9	72
22	Reliability investigation and interfacial reaction of ball-grid-array packages using the lead-free Sn-Cu solder. <i>Journal of Electronic Materials</i> , <b>2004</b> , 33, 1190-1199	1.9	66
21	Phase analysis and kinetics of solid-state ageing of Pb-free Sn <sub>3</sub> .5Ag solder on electroless Ni <sub>3</sub> P substrate. <i>Surface and Interface Analysis</i> , <b>2004</b> , 36, 963-965	1.5	8
20	Experimental and finite element analysis of the shear speed effects on the Sn <sub>3</sub> Ag and Sn <sub>3</sub> Ag <sub>0</sub> Cu BGA solder joints. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2004</b> , 371, 267-276	5.3	65
19	Growth kinetics of Ni <sub>3</sub> Sn <sub>4</sub> and Ni <sub>3</sub> P layer between Sn <sub>3</sub> .5Ag solder and electroless Ni <sub>3</sub> P substrate. <i>Journal of Alloys and Compounds</i> , <b>2004</b> , 376, 105-110	5.7	54
18	Intermetallic compound layer growth at the interface between Sn <sub>3</sub> CuNi solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , <b>2004</b> , 381, 151-157	5.7	84
17	Effect of reflow time on interfacial reaction and shear strength of Sn <sub>3</sub> .7Cu solder/Cu and electroless Ni <sub>3</sub> P BGA joints. <i>Journal of Alloys and Compounds</i> , <b>2004</b> , 385, 192-198	5.7	50
16	Effects of copper insert layer on the properties of friction welded joints between TiAl and AISI 4140 structural steel. <i>Intermetallics</i> , <b>2004</b> , 12, 671-678	3.5	75

15	The joint properties of copper by friction stir welding. <i>Materials Letters</i> , <b>2004</b> , 58, 1041-1046	3.3	200
14	Void Free Friction Stir Weld Zone Of The Dissimilar 6061 Aluminum And Copper Joint By Shifting The Tool Insertion Location. <i>Materials Research Innovations</i> , <b>2004</b> , 8, 93-96	1.9	33
13	Effect of Microstructure on Mechanical Properties of Friction-Welded Joints between Ti and AISI 321 Stainless Steel. <i>Materials Transactions</i> , <b>2004</b> , 45, 2805-2811	1.3	30
12	The Joint Characteristics of Friction Stir Welded AZ91D Magnesium Alloy. <i>Materials Transactions</i> , <b>2003</b> , 44, 917-923	1.3	67
11	Intermetallic compound layer formation between Sn3.5 mass %Ag BGA solder ball and (Cu, immersion Au/electroless Ni/P/Cu) substrate. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2003</b> , 14, 487-493	2.1	34
10	Mechanical properties of copper to titanium joined by friction welding. <i>Journal of Materials Science</i> , <b>2003</b> , 38, 1281-1287	4.3	20
9	Growth of an intermetallic compound layer with Sn-3.5Ag-5Bi on Cu and Ni-P/Cu during aging treatment. <i>Journal of Electronic Materials</i> , <b>2003</b> , 32, 1195-1202	1.9	76
8	Effects of fine fiber structures on the mechanical and electrical properties of cold rolled Cu-Ag sheet. <i>Journal of Materials Science Letters</i> , <b>2003</b> , 22, 1751-1754		8
7	Investigation of interfacial reactions between Sn5Bi solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , <b>2003</b> , 359, 202-208	5.7	70
6	Effect of Surface Finishes on Ball Shear Strength in BGA Joints with Sn-3.5 mass%Ag Solder. <i>Materials Transactions</i> , <b>2002</b> , 43, 751-756	1.3	32
5	Effect of Isothermal Aging on Ball Shear Strength in BGA Joints with Sn-3.5Ag-0.75Cu Solder. <i>Materials Transactions</i> , <b>2002</b> , 43, 1858-1863	1.3	60
4	The Effect of Bi Concentration on Wettability of Cu Substrate by Sn-Bi Solders. <i>Materials Transactions</i> , <b>2001</b> , 42, 751-755	1.3	46
3	Characterization of the thermal conductivity and mechanical properties of sheath alloy materials for Bi-2223 superconductor tapes. <i>IEEE Transactions on Applied Superconductivity</i> , <b>2001</b> , 11, 3277-3280	1.8	4
2	Effects of silver additions on the mechanical properties and resistance to thermal shock of YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-<math>\delta</math></sub> superconductors. <i>Cryogenics</i> , <b>1999</b> , 39, 107-113	1.8	26
1	Atmospheric-Pressure Plasma Sintering of Silver Nanopaste Screen-Printed on PI87-94		